

1. General description

WG20R135W1 uses advanced Fine Trench Field-stop technology IGBT with monolithic body diode in TO-247 package. This device is part of Reverse-Conducting of IGBTs, which represents an optimum compromise between conduction and switching losses to maximize the efficiency for soft commutation.



2. Features and benefits

- Reverse Conducting IGBT with Monolithic Body Diode
- Maximum Junction Temperature 175 °C
- Low Conduction Losses
- Positive Temperature efficient for Easy Parallel Operating
- EMI Improved Design

3. Applications

- Microwave ovens
- Induction heating
- Resonant converters
- Soft switching applications

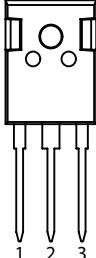
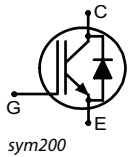
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Notes	Value			Unit	
V_{CE}	Collector-emitter voltage, $T_j \geq 25\text{ °C}$		1350			V	
I_C	DC collector current, limited by $T_{j(max)}$ $T_C = 100\text{ °C}$		20			A	
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}; I_C = 20\text{ A}; T_j = 25\text{ °C}$		-	1.8	2.2	V

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		 sym200
2	C	collector		
3	E	emitter		
mb	C	mounting base; connected to collector		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WG20R135W1	TO247	WG20R135W1Q	Tube	30	SOT429	25-Mar-2013

7. Marking

Table 4. Marking codes

Type number	Marking codes
WG20R135W1	G20R135 W1

8. Limiting values

Table 5. Limiting values

Symbol	Parameter	Notes	Value	Unit
V_{CE}	Collector-emitter voltage, $T_j \geq 25\text{ °C}$		1350	V
I_C	DC collector current, limited by $T_{j(max)}$ $T_C = 25\text{ °C}$ $T_C = 100\text{ °C}$		40 20	A
$I_{C(puls)}$	Pulsed collector current, t_p limited by $T_{j(max)}$		60	A
I_{CSM}	Non repetitive peak collector current ⁽¹⁾		200	A
-	Turn off safe operating area $V_{CE} \leq 1350\text{ V}$, $T_j \leq 175\text{ °C}$, $t_p = 1\text{ }\mu\text{s}$		60	A
I_F	Diode forward current, limited by $T_{j(max)}$ $T_C = 25\text{ °C}$ $T_C = 100\text{ °C}$		40 20	A
I_{Fpuls}	Diode pulsed current, t_p limited by $T_{j(max)}$		60	A
V_{GE}	Gate-emitter voltage		± 20	V
P_{tot}	Power dissipation $T_C = 25\text{ °C}$ Power dissipation $T_C = 100\text{ °C}$		300 150	W
T_{stg}	Storage temperature		-55 to +150	°C
T_{jmax}	Maximum operating junction temperature		175	°C
-	Peak soldering temperature		260	°C
M	Mounting Torque with washer		0.55	Nm

⁽¹⁾ capacitor charging saturation current limited by $T_{jmax} < 175\text{ °C}$ and $t_p < 3\mu\text{s}$

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-c)}$	IGBT thermal resistance from junction to case			-	0.5	-	K/W
$R_{th(j-c)}$	Diode thermal resistance from junction to case			-	0.5	-	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient			-	40	-	K/W

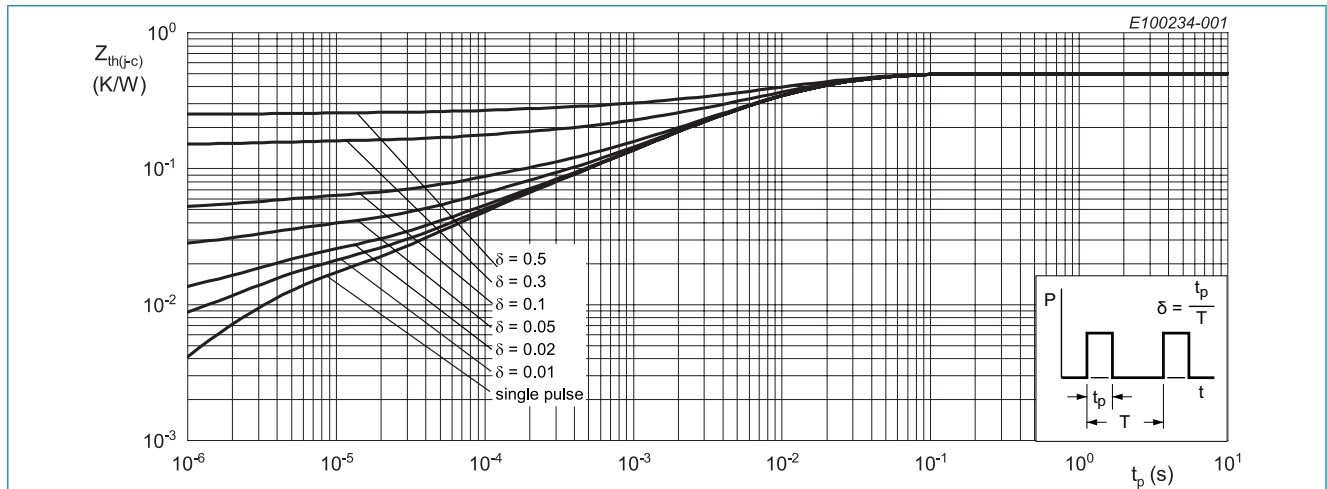


Fig. 1. Transient thermal impedance from junction to case as a function of pulse duration; IGBT

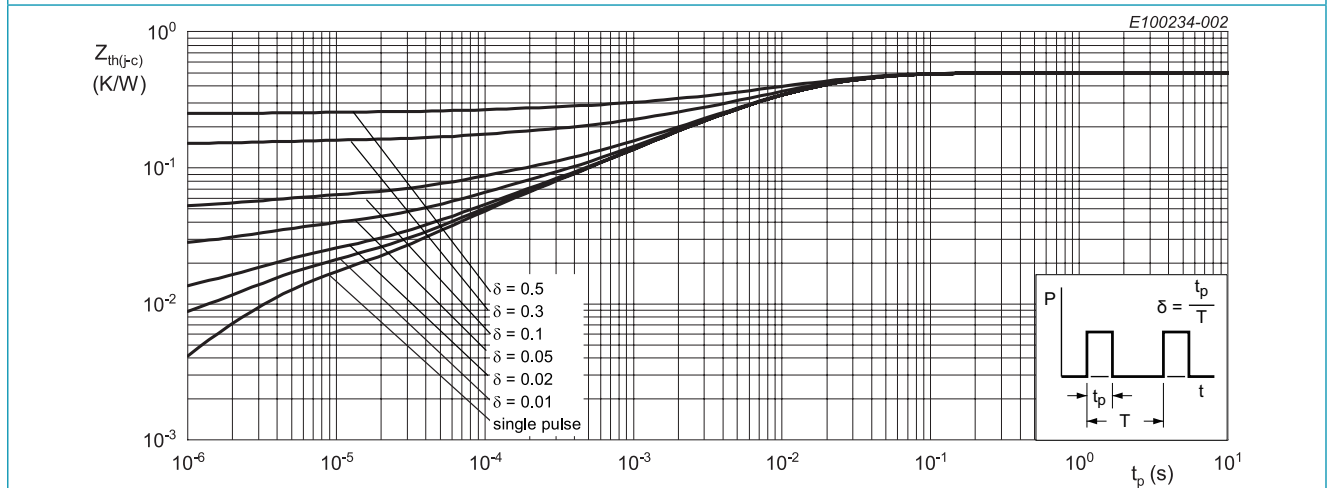


Fig. 2. Transient thermal impedance from junction to case as a function of pulse duration; Diode

10. Characteristics

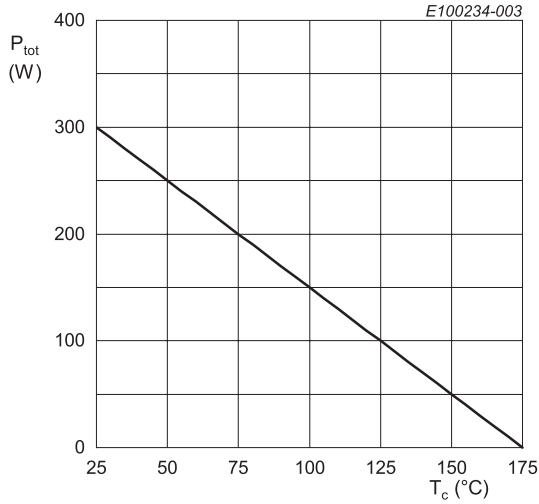
Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
BV_{CES}	Collector-emitter breakdown voltage	$V_{GE} = 0\text{ V}; I_C = 1\text{ mA}$		1350	-	-	V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}; I_C = 20\text{ A}; T_j = 25\text{ °C}$		-	1.8	2.2	V
		$V_{GE} = 15\text{ V}; I_C = 20\text{ A}; T_j = 175\text{ °C}$		-	2.35	-	V
V_F	Diode forward voltage	$V_{GE} = 0\text{ V}; I_F = 20\text{ A}; T_j = 25\text{ °C}$		-	1.9	-	V
		$V_{GE} = 0\text{ V}; I_F = 20\text{ A}; T_j = 175\text{ °C}$		-	2.2	-	V
$V_{GE(th)}$	Gate-emitter threshold voltage	$I_C = 0.5\text{ mA}; V_{CE} = V_{GE}$		4.5	5.5	6.5	V
I_{CES}	Zero gate voltage collector current	$V_{CE} = 1350\text{ V}; V_{GE} = 0\text{ V}; T_j = 25\text{ °C}$		-	-	100	μA
		$V_{CE} = 1350\text{ V}; V_{GE} = 0\text{ V}; T_j = 175\text{ °C}$		-	0.6	-	mA
g_{fs}	Transconductance	$V_{CE} = 20\text{ V}; I_C = 20\text{ A}$		-	21	-	S
Dynamic characteristics							
C_{ies}	Input capacitance	$V_{CE} = 30\text{ V}; V_{GE} = 0\text{ V}; f = 1\text{ MHz}; T_j = 25\text{ °C}$		-	2187	-	pF
C_{oes}	Output capacitance			-	42	-	pF
C_{res}	Reverse transfer capacitance			-	22	-	pF
Q_G	Gate charge	$V_{CC} = 1080\text{ V}; I_C = 20\text{ A}; V_{GE} = 15\text{ V}; T_j = 25\text{ °C}$		-	98	-	nC

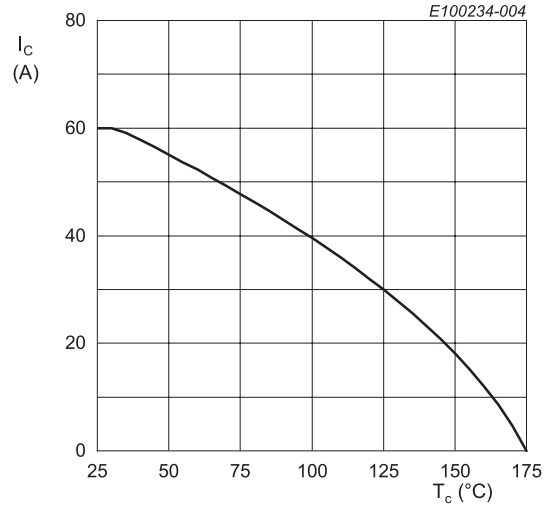
11. Switching Characteristics

Table 8. Switching Characteristics, Inductive Load

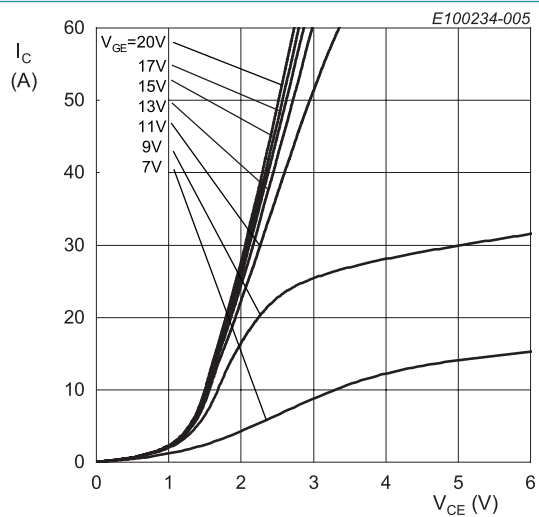
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
IGBT characteristics							
$t_{d(off)}$	Turn-off delay time	$T_j = 25\text{ °C}; I_C = 20\text{ A}; V_{GE} = 15\text{ V} / 0\text{ V}; R_G = 10\ \Omega; C_r = 300\text{ nF}; R = 2\ \Omega$		-	93	-	nS
t_f	Fall time			-	74	-	nS
E_{off}	Turn-off energy			-	54	-	μJ
$t_{d(off)}$	Turn-off delay time	$T_j = 175\text{ °C}; I_C = 20\text{ A}; V_{GE} = 15\text{ V} / 0\text{ V}; R_G = 10\ \Omega; C_r = 300\text{ nF}; R = 2\ \Omega$		-	94	-	nS
t_f	Fall time			-	89	-	nS
E_{off}	Turn-off energy			-	102	-	μJ



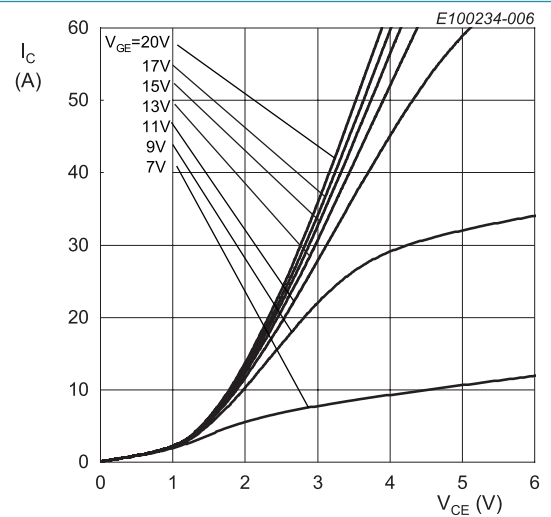
$T_j \leq 175\text{ }^\circ\text{C}$
Fig. 3. Power dissipation as a function of case temperature



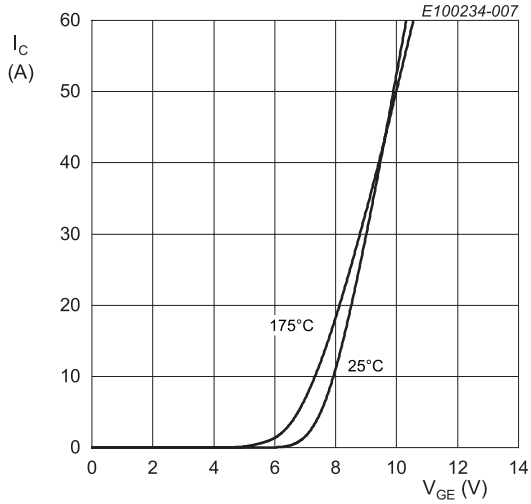
$V_{GE} \geq 15\text{ V}; T_j \leq 175\text{ }^\circ\text{C}$
Fig. 4. Collector current as a function of case temperature



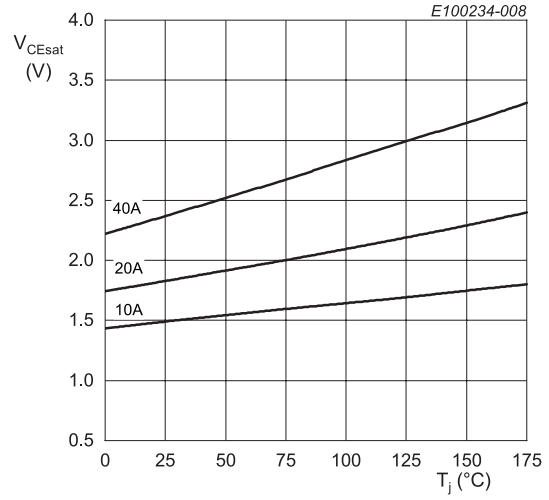
$T_j = 25\text{ }^\circ\text{C}$
Fig. 5. Typical output characteristic



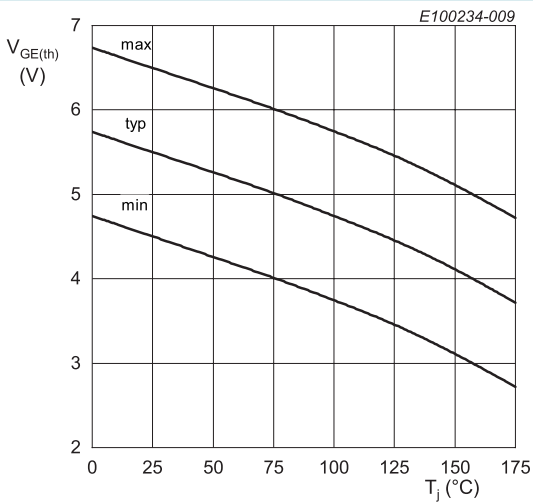
$T_j = 175\text{ }^\circ\text{C}$
Fig. 6. Typical output characteristic



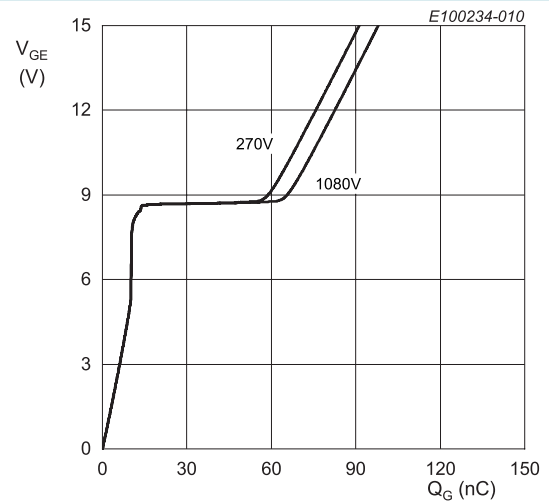
$V_{CE} = 20$ V
Fig. 7. Typical transfer characteristic



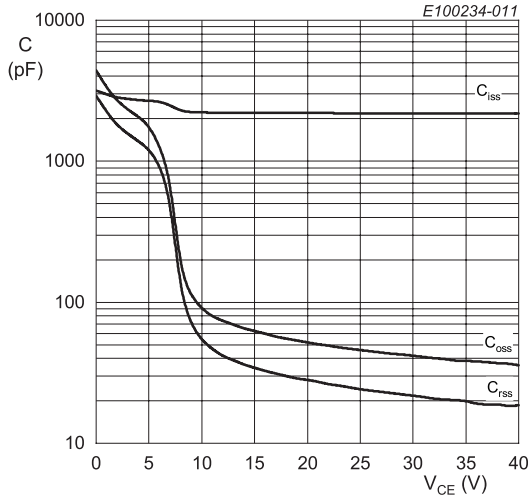
$V_{GE} = 15$ V
Fig. 8. Typical collector-emitter saturation voltage as a function of junction temperature



$I_C = 500$ µA
Fig. 9. Gate-emitter threshold voltage as a function of junction temperature



$I_C = 20$ A
Fig. 10. Typical gate charge



$V_{GE} = 0 \text{ V}; f = 1 \text{ MHz}$

Fig. 11. Typical capacitance as a function of collector-emitter voltage

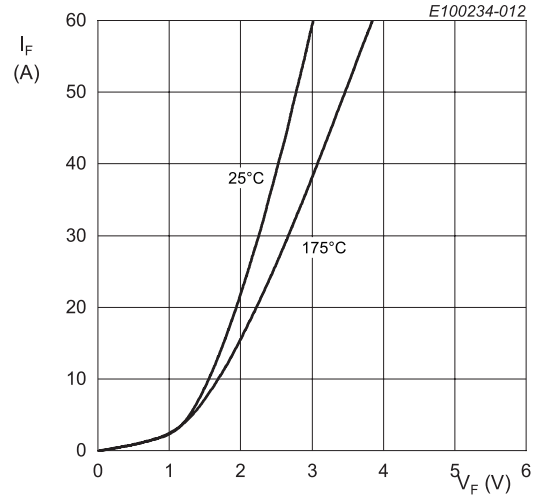
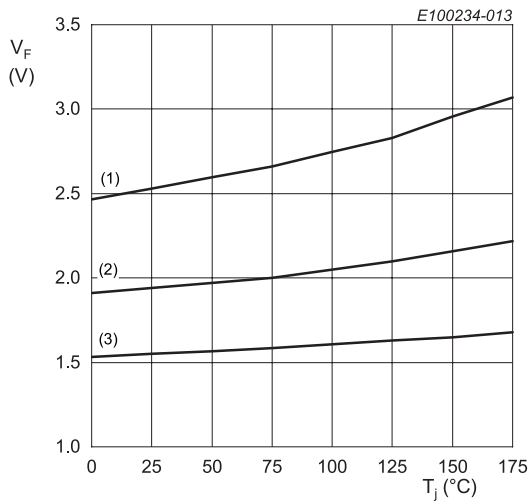
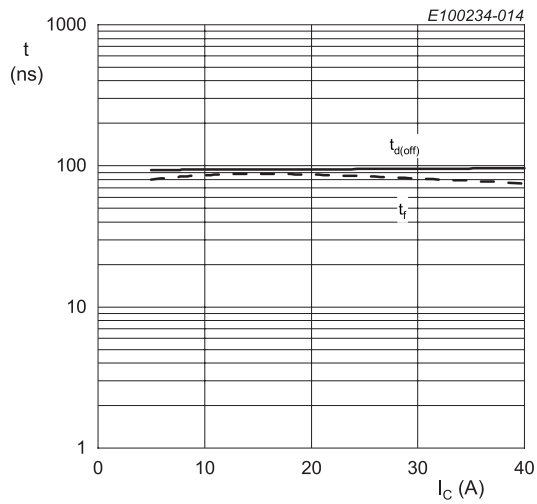


Fig. 12. Typical diode forward current as a function of forward voltage



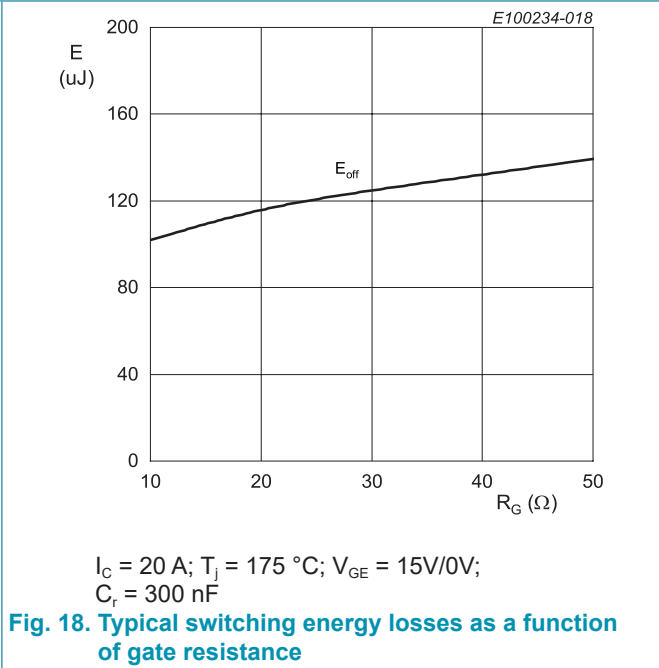
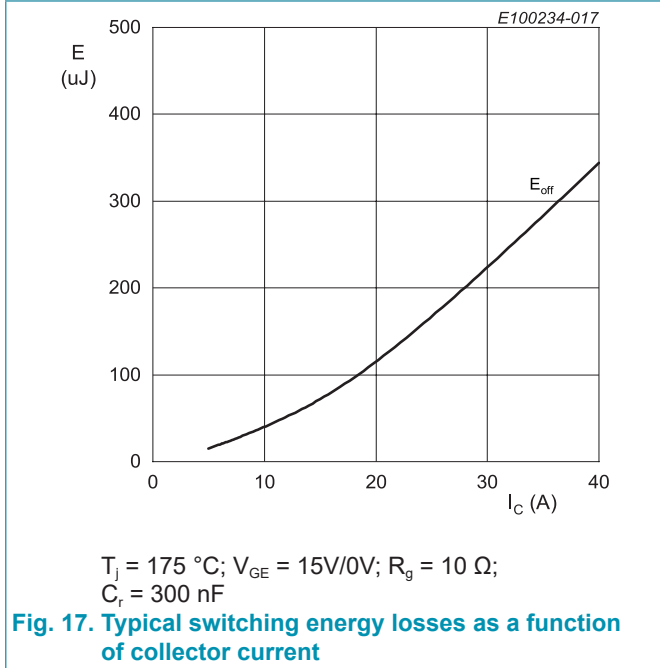
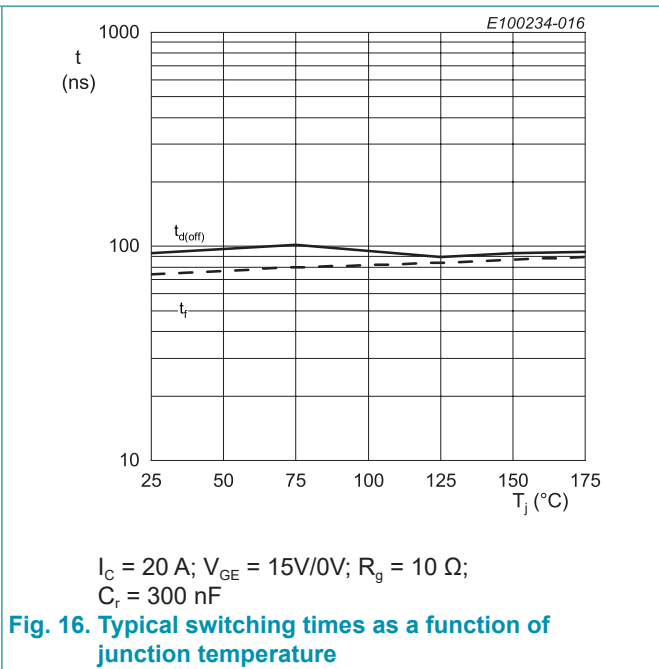
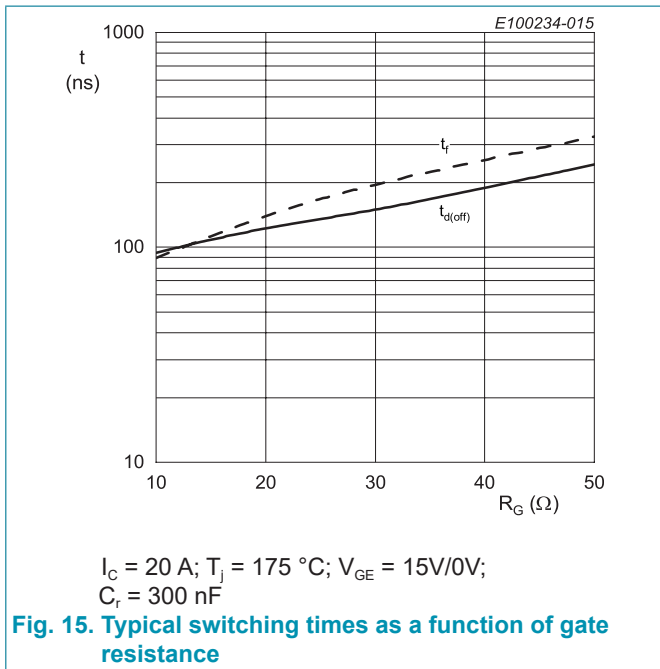
- (1) $I_F = 40 \text{ A}$
- (2) $I_F = 20 \text{ A}$
- (3) $I_F = 10 \text{ A}$

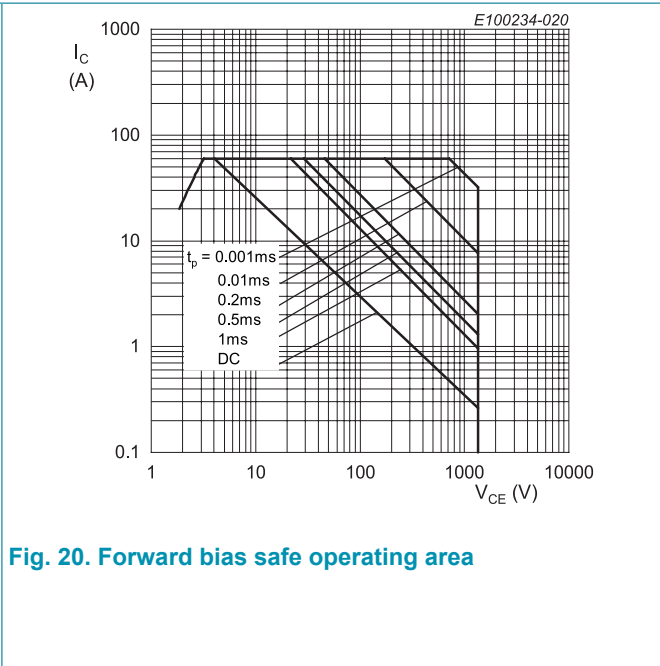
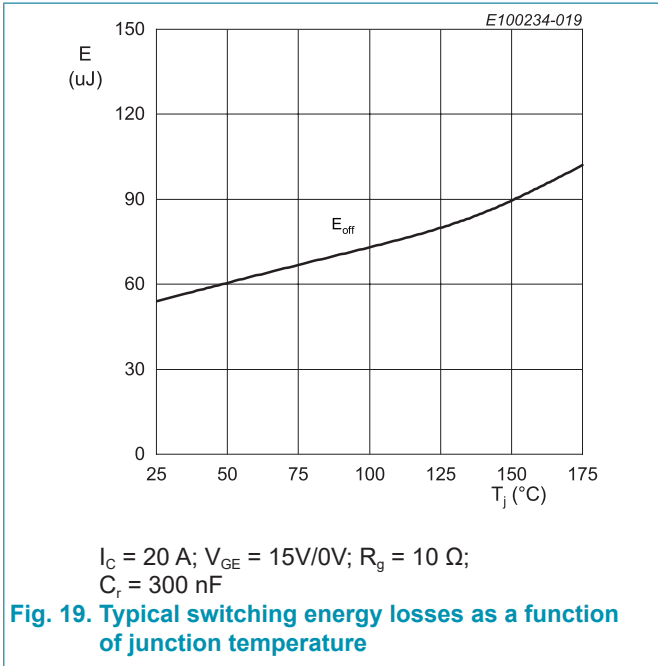
Fig. 13. Typical diode forward voltage as a function of junction temperature



$T_j = 175 \text{ °C}; V_{GE} = 15\text{V}/0\text{V}; R_g = 10 \text{ } \Omega;$
 $C_r = 300 \text{ nF}$

Fig. 14. Typical switching times as a function of collector current

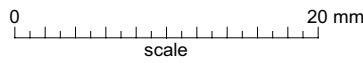
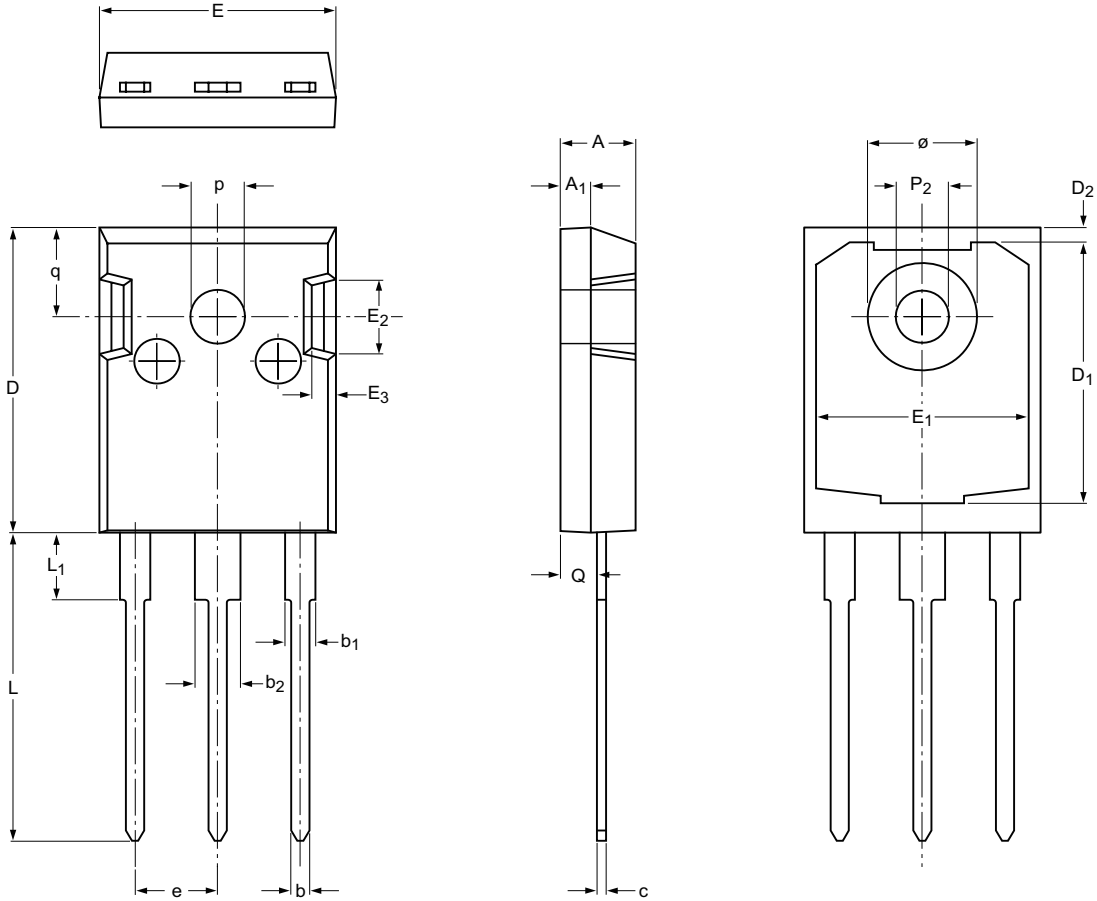




12. Package outline

Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 3-lead TO-247

SOT429



Dimensions (mm are the original dimensions)

Unit ⁽¹⁾	A	A ₁	b	b ₁	b ₂	c	D	D ₁	D ₂	E	E ₁	E ₂	E ₃	e ⁽¹⁾	L	L ₁	P ₂	p	Q	q	ø	
max	5.20	2.10	1.40	2.20	3.20	0.70	20.6	17.68	1.20	15.75	14.22	5.20	1.80	5.45	20.90	4.75	3.60	3.70	2.60	6.18	7.30	
nom																						
min	4.70	1.90	1.00	1.80	2.80	0.50	20.3	17.28	0.80	15.45	13.82	4.80	1.40		20.40	4.25	3.40	3.50	2.20	5.78	7.10	

Note

1. Basic spacing between centers.

sot429_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT429		TO-247			04-09-14- 13-03-25

13. Dynamic test circuit, waveforms and definition

Dynamic test circuit, waveforms and definition

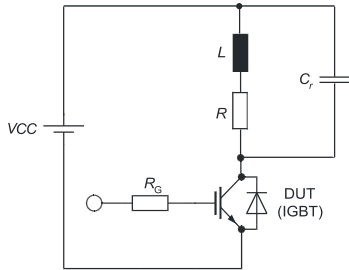


Figure A: Dynamic test circuit (Resonant capacitor, C_r ; Damping resistor, R)

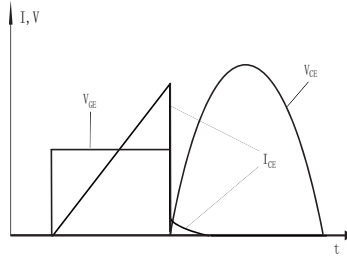


Figure B: Typical switching behavior in resonant applications

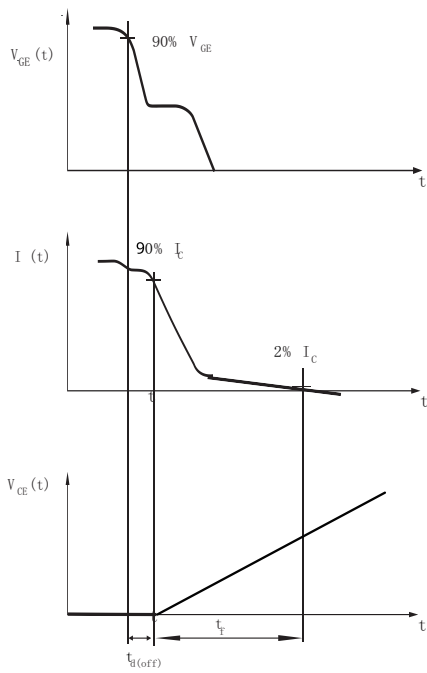
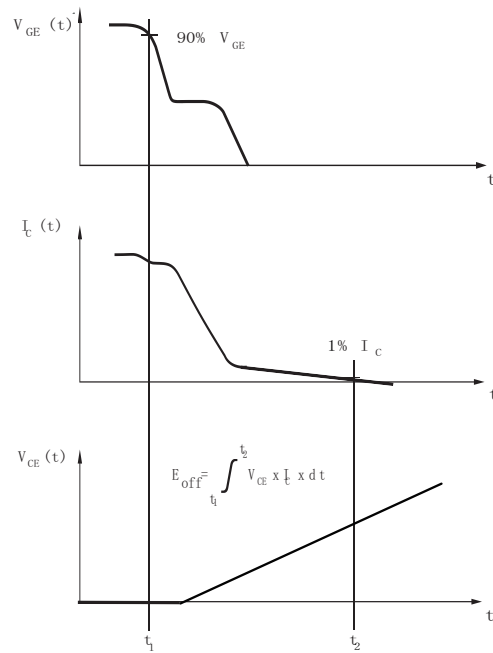


Figure C: Definition of switching time and losses



14. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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Date of release: 09 September 2024

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